

AMENDMENTS TO THE SPECIFICATION AND ABSTRACT

In the Specification:

Page 2

Please **amend** the paragraph beginning on line 10 as follows:

In order to solve the above-described problem associated with mount technology using flip chip bonding, there is a remarkable tendency that the size of a semiconductor device is ~~made as to~~ be substantially equal as that to that of a semiconductor element. A package of such a semiconductor device is generally called a CSP (chip size package or chip scale package). Examples of CSP are described in JP-A-6-504408, Technical Report of the Institute of Electronics, Information and Communication Engineers "Development on Tape BGA type CSP", CPM96-121, ICD96-160 (December, 1996) and the like.

Please **amend** the paragraph beginning on line 22 and bridging page 3 as follows:

~~The~~As noted above, the size of a conventional package for a CSP semiconductor device is approximately equal to the size of a semiconductor element. Namely, a sheet-shaped member made of a film base material formed with conductive wiring lines and lands is attached to the surface of a semiconductor element with adhesive, and external terminals are formed in a projected area of the principal surface of the semiconductor element.

Page 3

Please **amend** the paragraph beginning on line 3 as follows:

With conventional CSP techniques ~~that~~in which external terminals are disposed in the projected area of the principal surface of a semiconductor element, metal bumps such as solder bumps are used as the external terminals and connected to a printed circuit board. A problem associated with CSP having such a structure is a connection reliability of solder bumps.

Please **amend** the paragraph beginning on line 20 and bridging page 4 as follows:

Strain generated in the bump is concentrated ~~upon near at~~close to the bonding area between the bump and a land of a semiconductor device or a bonding pad of a printed circuit board. If such a temperature change is repeated, a crack may be formed in the bonding area. The crack formed in the bonding area of the bump gradually grows and the bonding area of the bump is ultimately broken. As the bump as the external terminal is broken, electrical connection between the semiconductor device and an external apparatus via external terminals cannot be maintained. Reliability of semiconductor devices is therefore lowered considerably.

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Please **amend** the paragraph beginning on line 18 and bridging page 9 as follows:

The ~~projection~~protective film is intervened between the land and the passivation film on the semiconductor element surface. The protective film is made

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of resin material which generally has a smaller elastic modulus than those of the materials of the land and external terminal. Since the protective film having a smaller elastic modulus is intervened between the land to be bonded to the external terminal and the passivation film on the semiconductor element surface, deformation to be generated in the external terminal because of a linear expansion coefficient difference between the semiconductor device and printed circuit board can be relaxed by the deformation of the protective film. It is therefore possible to reduce strain to be generated in the bonding areas on both sides of the semiconductor device and printed circuit board.

In the Abstract:

Please cancel the original Abstract and replace it with the new Abstract attached hereto as Appendix A.